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No.N	06-05038	3 P1 P2 P10	BB02-HC031-KB1-603000	CONNECTOR, HEADER, MALE, STRAIGHT, 1 ROW, 3 PINS, PITCH 2.54mm, PTH	GRADCONN	BB02-HC031-KB1-603000		+105DEGC	ROHS_COMPLIANT
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00100.0000 <td></td> <td></td> <td></td> <td></td> <td>MURATA</td> <td>MMER20 2700B14</td> <td></td> <td>REDECC</td> <td>ROHS COMPLIANT</td>					MURATA	MMER20 2700B14		REDECC	ROHS COMPLIANT
9. 18 Mail 3.18 SIGNO MOLINAL SURVAY MOLECULAR MOLINAL SURVAY MOLECULAR MOLINAL M							0402		ROHS COMPLIANT
0.1230 1.11 2.34 RSIGNT HIDE VILLA 22, SV/SK 000K 90, SV/SGC (200, SMD MANUAC URER SLICE SSIGN 50, SUL 24, SV/SK 000K 94, J-2000 MO MO MISC									ROHS COMPLIANT
Ind DecisionIndexConstructionMain Decision </td <td></td> <td>1 R11</td> <td>2.2k</td> <td>RESISTOR. THICK FILM. 2.2k5%/+5%. 0.063W. 50V55DEGC/+155DEGC. 0402. SMD</td> <td>MANUFACTURER SELECTION</td> <td></td> <td></td> <td>+155DEGC</td> <td>ROHS COMPLIANT</td>		1 R11	2.2k	RESISTOR. THICK FILM. 2.2k5%/+5%. 0.063W. 50V55DEGC/+155DEGC. 0402. SMD	MANUFACTURER SELECTION			+155DEGC	ROHS COMPLIANT
0.2324 2.4475 0.235 0.45770 0.235 0.45770 0.2370 0.45770 0.2370 0.457700 0.457	02-01199	1 R12	1.8pF	CAPACITOR, CERAMIC C0G/NP0, 1.8pF, 50V, -0.1pF/+0.1pF, -55DEGC/+125DEGC, 0402, SMD	MURATA	GJM1555C1H1R8BB01D	0402	+125DEGC	ROHS COMPLIANT
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0.12320 1 kT									ROHS_COMPLIANT
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01-2320 1.820 MANUFACTURE SLECTION MANUFACTURE SLECTION MANUFACTURE SLECTION SUSTOR, MAIL 2000, MI-1/1000, SUM, MI-1/2000, MI Mole				REDISTUR, THILK FILM, 4. /K, -5%/+5%, 0.063W, 50V, -55DEGC/155DEGC, 0402, SMD					
10.2220 18.22 <				LANNY DESISTRE THICK FILM 100 -1%/41% 0.053W 50V -SSDEGC/41SSDEGC 0402 SMD					ROHS COMPLIANT
10.2320 18.24 18.24 18.24 18.24 18.24 18.24 18.25 <									ROHS COMPLIANT
01-2320APX 28 A98 A99APX 28 A90 A99 A99 A99 A99 A99 A99 A99 A99 A99									ROHS COMPLIANT
01-2323 1 R38 MAMPUAP TREE SILETION MAMPUAP TREE SILETION <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td>ROHS COMPLIANT</td>									ROHS COMPLIANT
01-2339 1 R32 R33 R			4.87k						ROHS_COMPLIANT
0.12.325 1.83 Constraint of the Constraint of									ROHS_COMPLIANT
01-2324 1 R4 NAM R54 SST0R FILCR FILL SQL, SQL, SQL, SQL, SQL, SQL, SQL, SQ									ROHS_COMPLIANT
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011377 1 552 0 0 PESTOR, THICK FILM, 0.1W, 75V, SSDEGC, 1455DECC, M03, SMO MAMURAL TURER SELECTION RESISTOR, M03, 0, 1/5X, 75V, 0.1W, M, 2/000pm 60.30 1.555DEC ROHING 0.12238 4 585 SER 5676 f6 0.0 RESISTOR, FILM, 100, 5/4/55DEC, 1455DECC, M03, SMO MAMURAL TURER SELECTION RESISTOR, M03, 0, 1/5X, 75V, 0.1W, M, 2/000pm 60.30 + 555BEC ROHING 0.12238 3 WIS SW2 SW3 108 C110/12286CT NICH COLON, M02/1428/25V, 0.055M, 50V, 0.056M, 50V, 50V, 0.056M, 50V, 50V, 0.056M, 50V, 0.057V, 0									ROHS COMPLIANT
01-2230 4 Sty Ste Sty									
0e0003 31 M92 SW3 0e007			-						
14-325 1 U1 Chilo 12,286,27 I (NICODON TROLLER, 2386,1.84* TO 3.84* U07ANE4P, 5MD TEXA INFINIT CHILO 12,1072,286,1.24* VOINAL-P SEDSG Roht COM 18-3726 14 MCROS MOST MULTICAL 2386,1.24** TO 3.84* U07ANE4.74* AUSA MCROS MOST MULTICAL 2386,1.24** TO 3.84* North COM MCROS MOST MULTICAL 2386,1.24** SeDSG MOST MULTICAL 2386,1.24** SeDSG MOST MOST MULTI							3402		ROHS_COMPLIANT
18-337 1 Val Mod2 SB0357/LU0 IC MeMORY, FASH, SEBML, MMUL, 15/W 70.36/, UX08, SM0 MAC 20, WT MACR0, WT MS2880357/LU0 US08 4505 (C R0H 20, WT 18-3511 1 US MAC12346/WT I. MeXD9346/WT I. MeXD9346/WT I. MeXD9346/WT TOPI243, SM0 TOPI243, SM0 TMAC12346/WT TOPI243, SM0 TOPI243, SM0 TMAC12346/WT TOPI243, SM0 TOPI243, SM0 TMAC12346/WT TOPI243, SM0 TOPI							VOEN48-EP		ROHS COMPLIANT
18-2531 105 TMAC 1294KPD718 INCRORPORCESSOR, TVAC SERIES MICROCONTROLLER, AMA (TRIX-M4, 29/VTO 5.8/S), TOP128, SMO TEXA INFLUMENTS TMAC 1294KPD718 TOP128 ABDEG ROH-5 18-2558 105 LM400403200C CANALO, EVERSION MICROFONDER/SHINT VICAT CREERES ALCROCONTROLLER, AMA (TRIX-M4, 29/VTO 5.8/S), TOP128, SMORTMUNENTS TMAC 1294KPD718 TMAC 1294KPD718 SMORT SMORT </td <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td>ROHS COMPLIANT</td>									ROHS COMPLIANT
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18-2028 3 U8 09/10 Strat Wird(712458) UG/TAL_LOGIC, 4bit UAL-SUPPI V8 US TRANSCEDER 3 STATE OUTPUT, 12/TO 3 6V, UG/PALE, SMD TEXA INSTRUMENTS StrAtward(712458) UG/TAL 458 DEG C RDH 2 12-00546 1 Y1 32.768/ht CIRISTAL, RESONATION, 32.768/ht									ROHS_COMPLIANT
1200546 1 Y1 32.768/kHz CRYSTAL, RESONATOR, 32.768/kHz, -20PP/M, 4200P/M, 4200EGC/485DEGC, SMD EPSON FC-135 32.7680/kA-AGO +85DEGC ROHS_COM 12-00757 1 Y2 24MHz CRYSTAL, CRYSTAL, OSCILLATOR, 24MHz, -15PP/M/DEGC/		1 U7							ROHS COMPLIANT
1200757 1 Y2 24MHz CNYSTAL OSCILLATOR, 24MHz, 15PPM/DEGC/+15PPM/DEGC,450EGC,5MD EP50N TSK-3225 24.0000MP15X-AC3 +850EGC R0H5_COM							UQFN16		ROHS COMPLIANT
									ROHS_COMPLIANT
12-00/45 1 YS 16MHz CRYSTAL, OSCILLATOR, 16MHz, -30PPM/DEGC, -40DEGC, -40DE									ROHS_COMPLIANT
	12-00745	1 Y3	16MHz	LKYSTAL, USLILLATUK, 16MHZ, -3UPPM/DEGC/+30PPM/DEGC, -40DEGC/+85DEGC, SMD	NIHON DEMPA KOGYO	NX3225GA-16.000M-STD-CRG-1		+85DEGC	ROHS_COMPLIANT

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